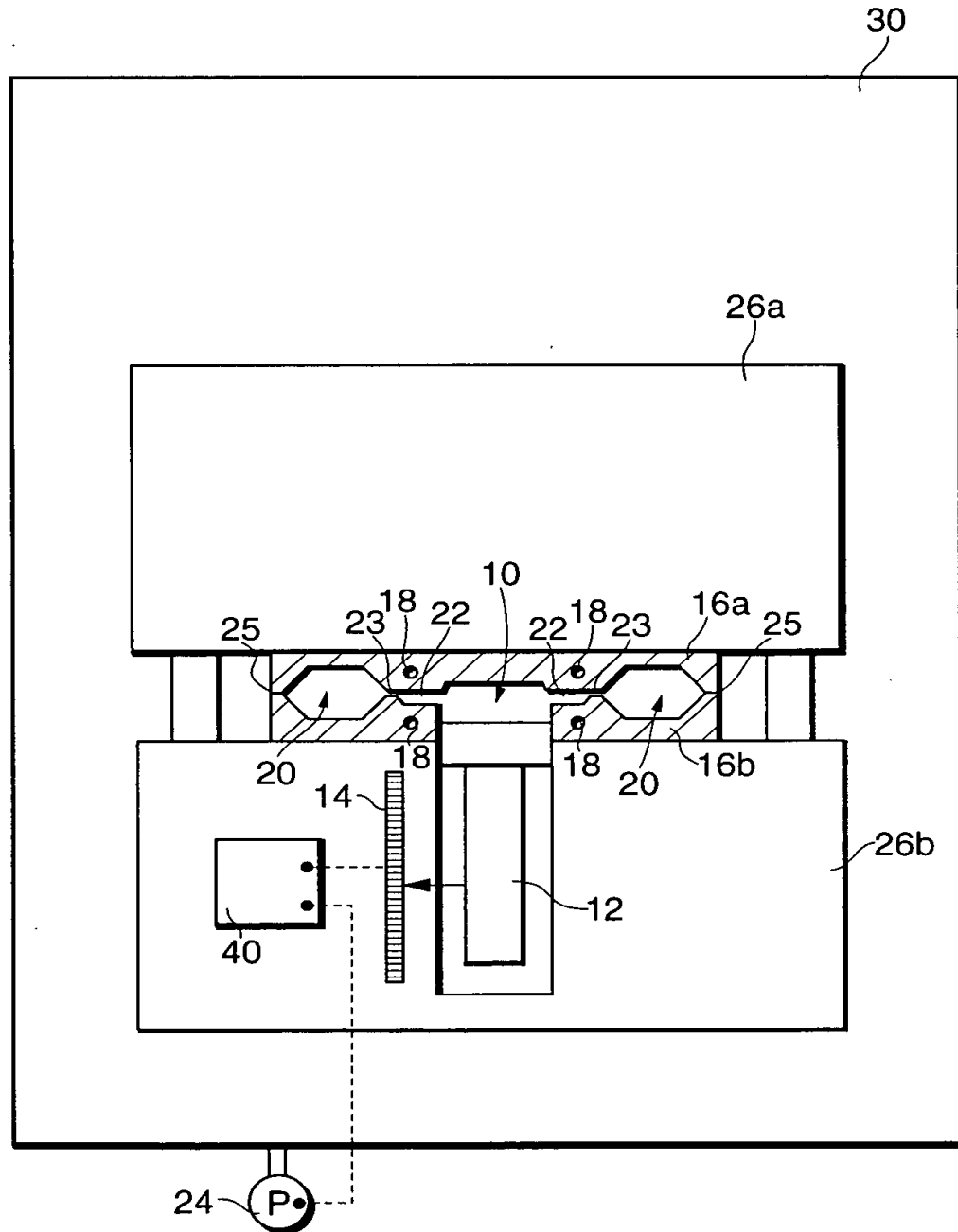


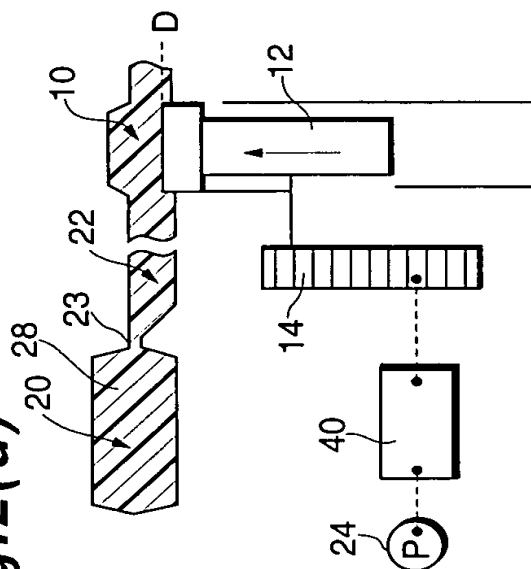
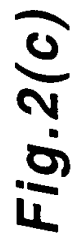
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**Fig. 1**



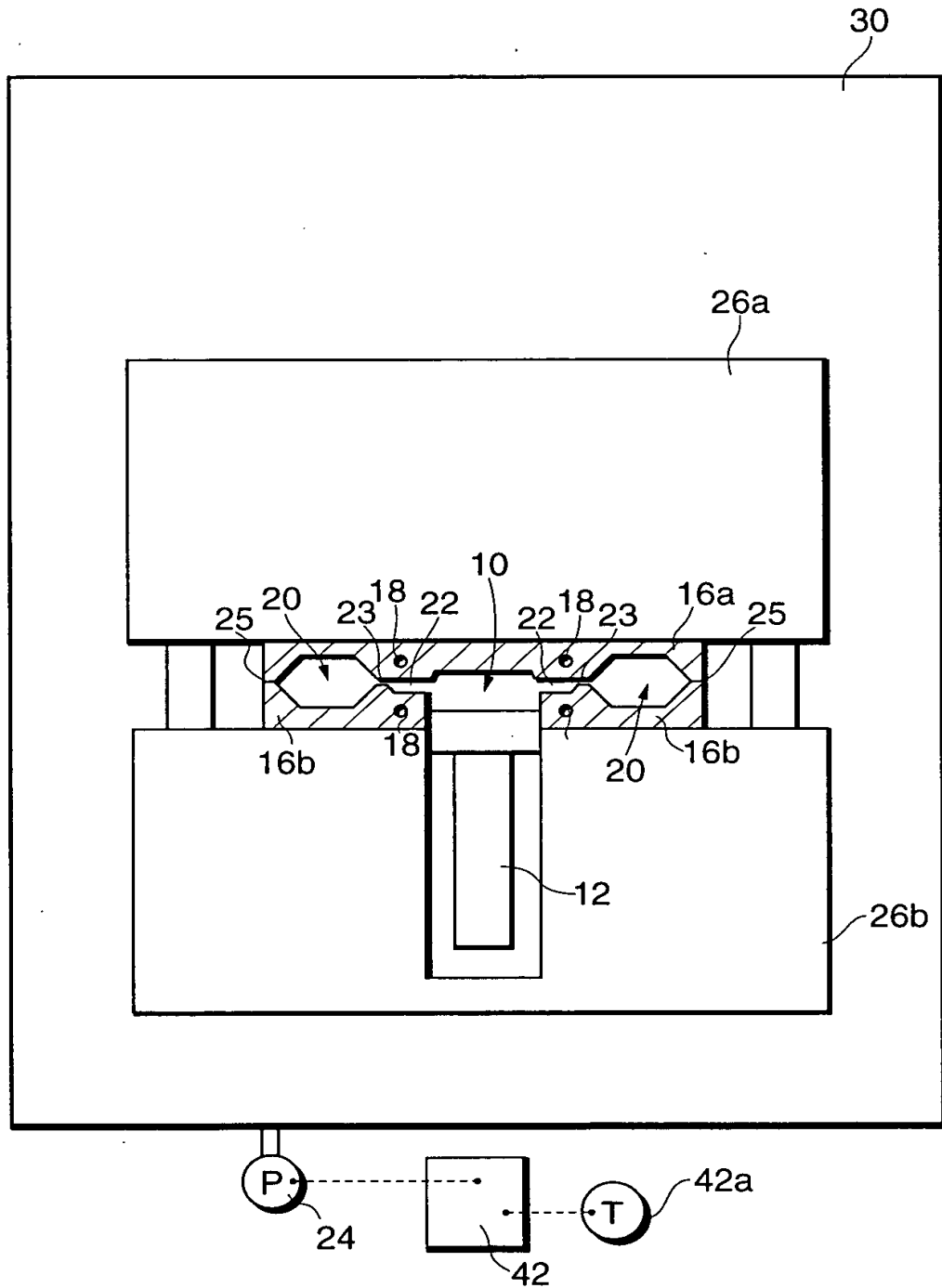


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**Fig.3**



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Fig. 4(a)

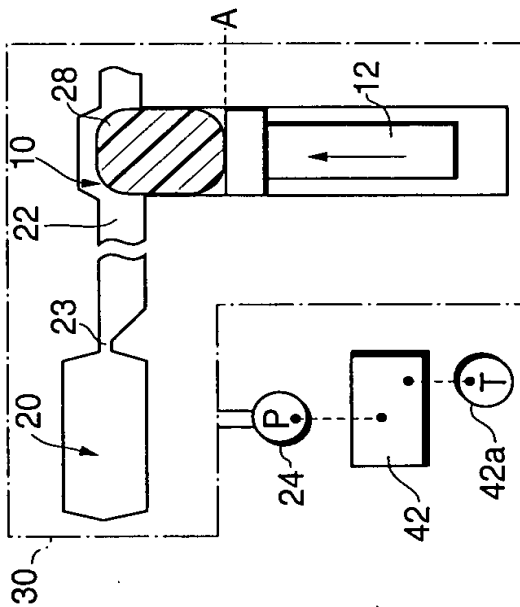


Fig. 4(b)

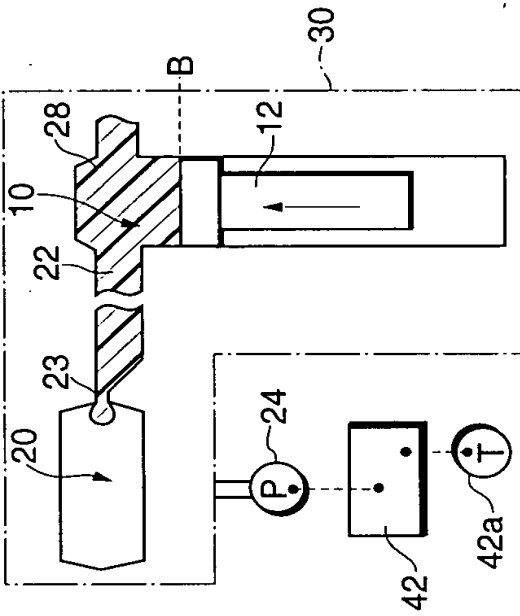


Fig. 4(c)

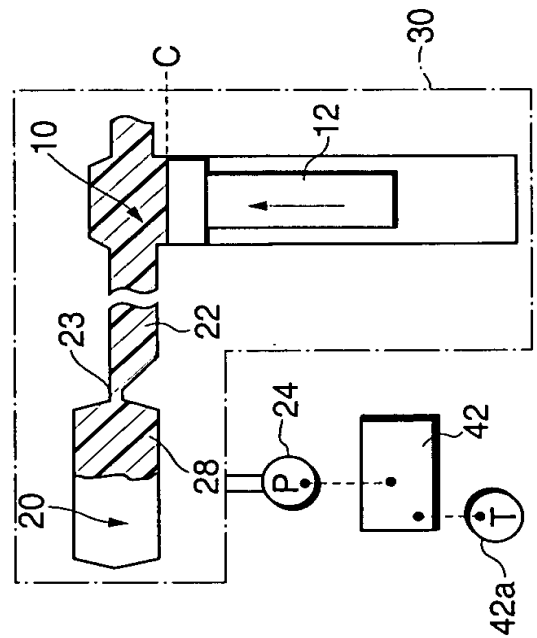
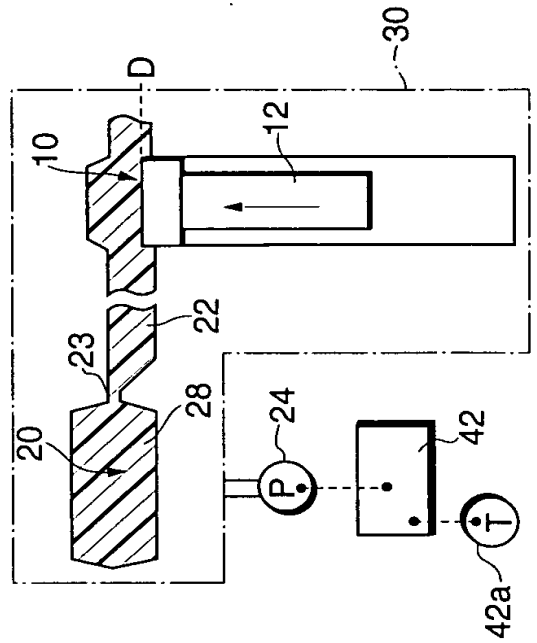
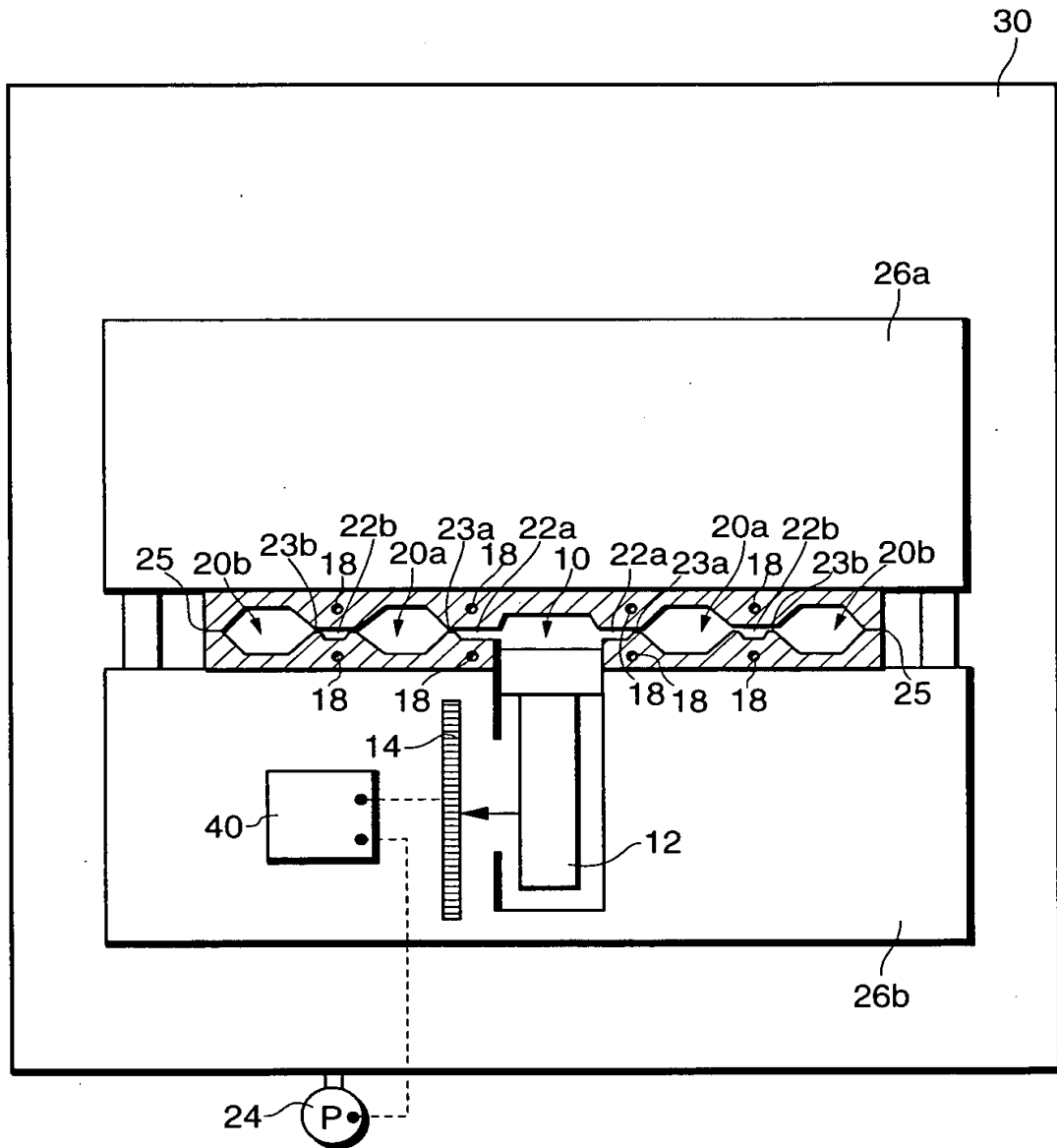


Fig. 4(d)



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**Fig.5**



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Fig. 6(b)

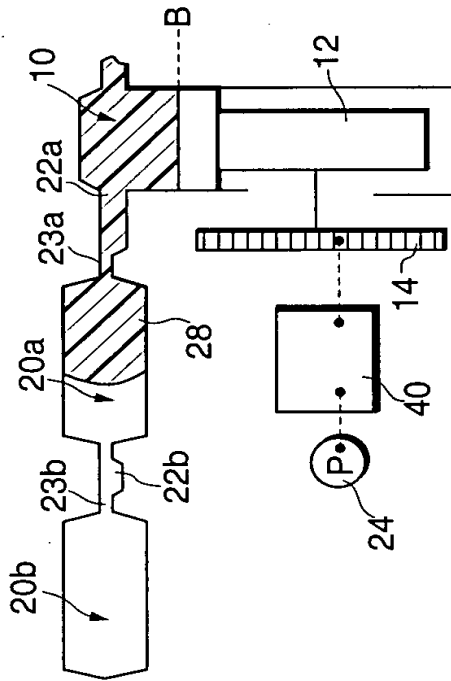


Fig. 6(d)

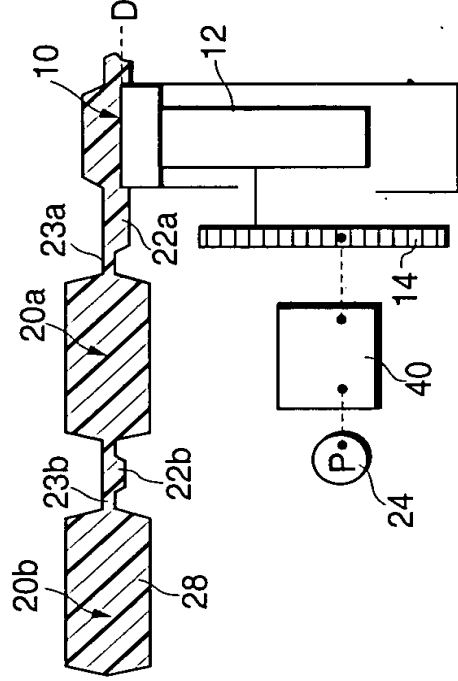


Fig. 6(a)

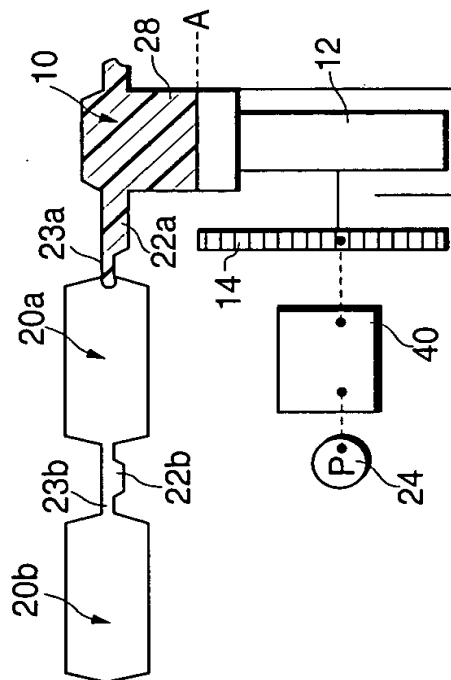
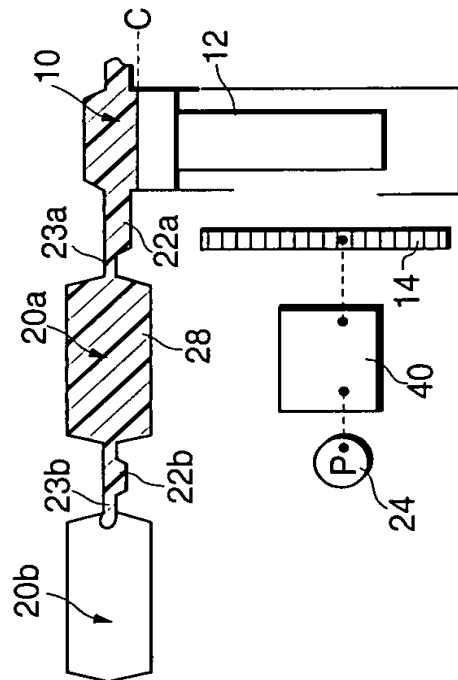


Fig. 6(c)



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**Fig.7**

